IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	**Material Composition Declaration** 	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-21.1	IPC Web Site for Information on IPC-1752 Standard **http://www.ipc.org/IPC-175x**	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company name* **onsemi**	Company unique ID	Unique ID Authority	**Response Date*** **2024-04-19**
Contact Name **Product-Env-Stewards**	Title - Contact Product Enviro Compliance	**Phone - Contact*** **NA**	**Email - Contact*** **Product-Env-Stewards@onsemi.com**
Authorized Representative* **Product-Env-Stewards**	Title - Representative Product Enviro Compliance	**Phone - Representative*** **NA**	**Email - Representative*** **Product-Env-Stewards@onsemi.com**

	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
		STK681-332-E	DC brush motor driver	2024-04-19		VN2	3400.0	mg	Each

Manufacturing Proccess Information

	Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature		Max Time at Peak Temperature		Number of Reflow Cycles
	Matte Tin (Sn) - annealed	**CU Alloy**	**NA**	**0**	C	**30**	seconds	**3**

Comments

For more information regarding material composition please refer to page 3

RoHS Material Composition Declaration		**Declaration Type ***	**Detailed**
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).		

Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a “RoHS restricted substance”) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components.Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form.Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph.If the Company and the Supplier enter into a written agreement with respect to the identified part,the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.

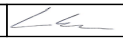
RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	**Supplier Acceptance ***	**Accepted**

Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

Exemption List Version	EL-2011/534/EU	

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature	**Rastislav Drska**		

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	1143.2	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		6.5162	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		43.4416	mg
			B	Nickel (Ni)	7440-02-0		2.0578	mg
			Supplier	Acrylic resins	Proprietary Data		0.8002	mg
			Supplier	Copper (Cu)	7440-50-8		40.5836	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		0.6859	mg
			Supplier	Aluminum (Al)	7429-90-5		1049.1146	mg
Chip Parts	9.46	mg	Supplier	Silver (Ag)	7440-22-4		0.4787	mg
			Supplier	Epoxy resins	129915-35-1		0.2431	mg
			Supplier	Tin (Sn)	7440-31-5		0.3916	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2479	mg
			Supplier	Ceramic	12013-47-7, 12047-27-7		2.4814	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		4.6222	mg
			B	Nickel (Ni)	7440-02-0		0.4844	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.0303	mg
			Supplier	Copper (Cu)	7440-50-8		0.4806	mg
Die	8.22	mg	Supplier	Silicon (Si)	7440-21-3		8.2068	mg
			Supplier	Polyimide	Proprietary Data		0.0132	mg
Die Attach	0.28	mg	Supplier	Silver (Ag)	7440-22-4		0.2156	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.0476	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.012	mg
			B	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0048	mg
Lead Frame	474.08	mg	Supplier	Tin (Sn)	7440-31-5		0.2844	mg
			Supplier	Copper (Cu)	7440-50-8		473.7955	mg
Mold Compound-Black	1757.27	mg		Brominated epoxy resin	proprietary data		35.1454	mg
			Supplier	Phenolic Resin	Proprietary Data		123.0089	mg
			B	Antimony Trioxide (Sb2O3)	1309-64-4		35.1454	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1230.089	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		333.8813	mg
Plating	0.95	mg	Supplier	Tin (Sn)	7440-31-5		0.5881	mg
			B	Nickel (Ni)	7440-02-0		0.3619	mg

Solder Ball	3.96	mg	Supplier	Silver (Ag)	7440-22-4		0.1105	mg
			Supplier	Tin (Sn)	7440-31-5		3.8269	mg
			B	Antimony (Sb)	7440-36-0		0.0032	mg
			Supplier	Copper (Cu)	7440-50-8		0.0194	mg
Wire Bond	2.58	mg	Supplier	Silicon (Si)	7440-21-3		0.0083	mg
			Supplier	Aluminum (Al)	7429-90-5		2.5717	mg